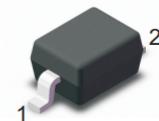


**Features**

- Low Forward Voltage Drop
- Guard Ring Construction for Transient Protection
- High Conductance
- Also Available in Lead Free Version


**Mechanical Data**

- Case: SOD-323
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 5.48mg / 0.00019oz

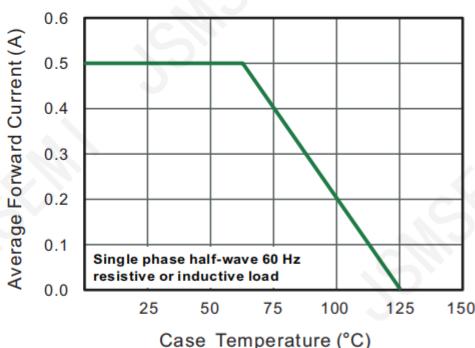
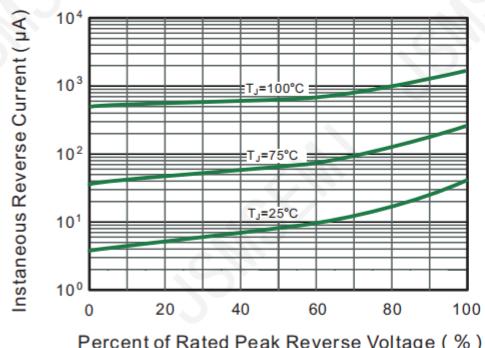
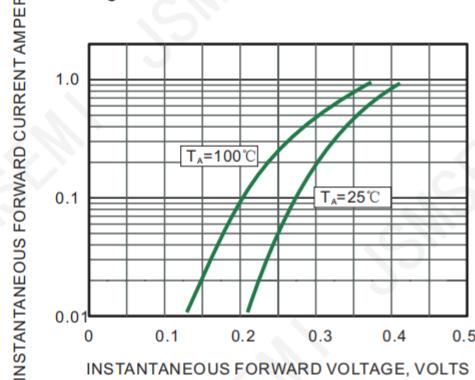
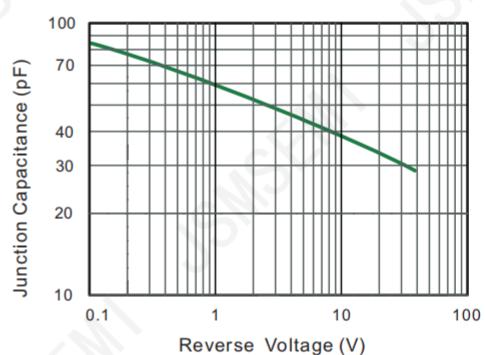
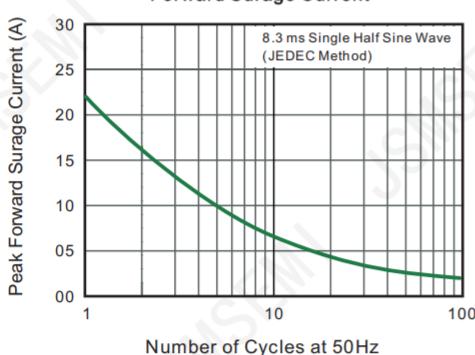
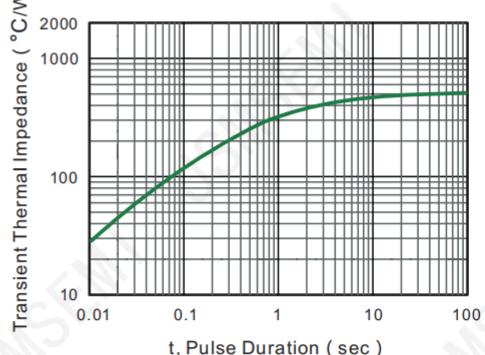
**Pining**

PIN	DESCRIPTION
1	Cathode
2	Anode

**Maximum Ratings and Electrical characteristics**

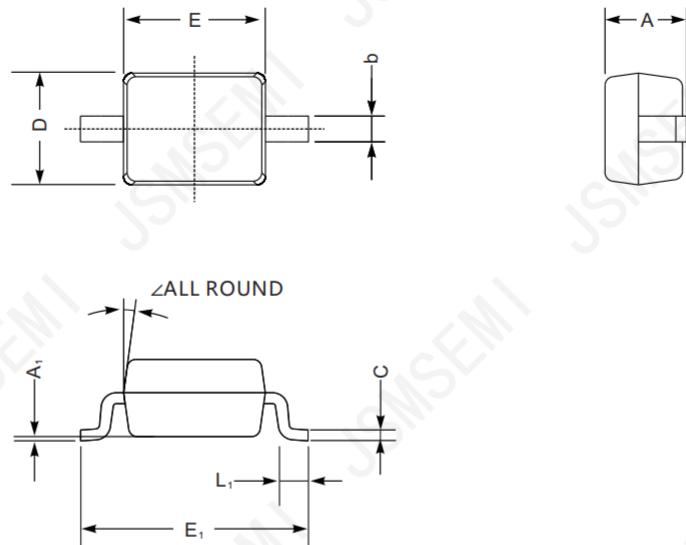
Ratings at 25°C ambient temperature unless otherwise specified.

Parameter	Symbols	PMEG3005AEA,115-JSM		Units
Peak Repetitive Reverse Voltage	$V_{RRM}$	30		V
RMS reverse voltage reverse voltage (DC)	$V_{RMS}$	21		V
Maximum DC Blocking Voltage	$V_{DC}$	30		V
Maximum Average Forward Current at $T_a=25^\circ C$	$I_o$	0.5		A
Peak Forward Surge Current, 8.3ms single half sine-wave super imposed on rated load (JEDEC method)	$I_{FSM}$	22		A
Maximum Instantaneous Forward Voltage	$V_F$	0.36 0.45 —		V
Reverse current	$I_R$	— 75 100 500 —		$\mu A$
Thermal Resistance, Junction to Ambient Air	$R_{JJA}$	500		$^\circ C/W$
Junction temperature	$T_j$	-55 ~ +125		$^\circ C$
Storage temperature	$T_{stg}$	-55 ~ +150		$^\circ C$

**Fig.1 Forward Current Derating Curve**

**Fig.2 Typical Reverse Characteristics**

**Fig.3 TYPICAL FORWARD VOLTAGE**

**Fig.4 Typical Junction Capacitance**

**Fig.5 Maximum Non-Repetitive Peak Forward Surge Current**

**Fig.6 Typical Transient Thermal Impedance**


## PACKAGE OUTLINE

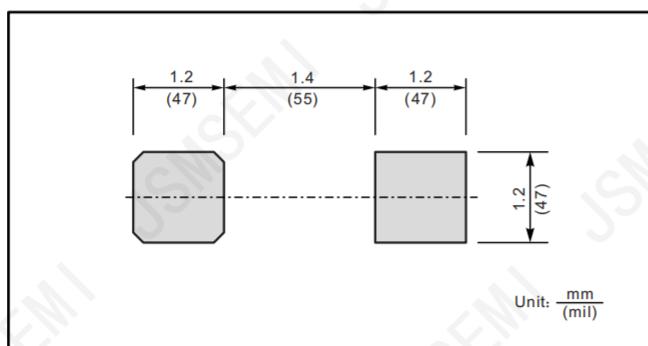
Plastic surface mounted package; 2 leads



SOD-323 mechanical data

UNIT		A	C	D	E	E <sub>1</sub>	b	L <sub>1</sub>	A <sub>1</sub>	∠
mm	max	1.1	0.15	1.4	1.8	2.75	0.4	0.45	0.2	9°
	min	0.8	0.08	1.2	1.4	2.55	0.25	0.2	—	
mil	max	43	5.9	55	70	108	16	16	8	9°
	min	32	3.1	47	63	100	9.8	7.9	—	

The recommended mounting pad size



## Revision History

Rev.	Change	Date
V1.0	Initial version	6/27/2021

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